

ABSTRACT OF THE DISCLOSURE

In a flip chip process, a wafer is provided with a plurality of chips therein. Each chip has an active surface on which are formed a plurality of bonding pads. A bump is formed on each bonding pad. A plurality of substrates respectively includes at least a package unit, wherein each package unit has a plurality of contact pads. The substrates are respectively mounted onto the wafer such that each package unit corresponds to one chip and the contact pads of the package unit are respectively connected to the corresponding bumps, wherein two neighboring substrates are separated by a gap. An underfill material fills between the wafer and the substrates, the underfill material being introduced through the gaps between the substrates and from the boundary of the wafer. The underfill material then is solidified. The substrates and the wafer are diced to form individualized packages.